

RoHS Compliant & Pb-Free Product

Typical Applications

- CDMA PCS Handsets
- GPS Receiver
- W-CDMA Handsets

1500MHz TO 2200MHz DOWNCONVERTER

General Purpose Downconverter

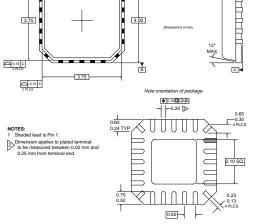
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- Commercial and Consumer Systems
- Portable Battery-Powered Equipment

Product Description

The RF2460 is a receiver front-end designed for the receive section of PCS CDMA and W-CDMA applications. It is designed to amplify and downconvert RF signals while providing 29dB of stepped gain control range and features digital control of LNA gain, mixer gain, and power down mode. A further feature of the chip is adjustable IIP3 of the LNA and mixer using an off-chip current setting resistor. Noise Figure, IP3, and other specs are designed to be compatible with the IS-98B for CDMA PCS communications. The IC is manufactured on an advanced Silicon Germanium Bi-CMOS process and is assembled in a 20-pin, QFN package with an exposed die flag.

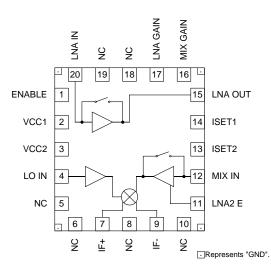


0.15 C A

2 PLCS

Optimum Technology Matching® Applied

🔲 Si BJT	GaAs HBT	GaAs MESFET
Si Bi-CMOS	SiGe HBT	Si CMOS
InGaP/HBT	GaN HEMT	SiGe Bi-CMOS



Functional Block Diagram

Package Style: QFN, 20-Pin, 4x4

Features

- Complete Receiver Front-End
- Stepped LNA/Mixer Gain Control
- Adjustable LNA/Mixer Bias Current
- 24dB Gain and 2.2dB Noise Figure at Maximum Cascade Gain

Ordering Information

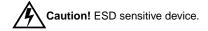
Greensboro, NC 27409, USA

RF2460	MPCS CDMA Low Noise Amplifier/Mixer 1500MHz				
	to 2200MHz Downconverter				
RF2460PCBA-41X	Fully Assembled Evaluation Board				
RF Micro Devices, In					
7628 Thorndike Road	Fax (336) 664 0454				

http://www.rfmd.com

Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	-0.5 to +5.0	V _{DC}
Input LO and RF Levels	+6	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



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Parameter		Specification)	Unit	Condition
Farameter	Min.	Тур.	Max.	Unit	Condition
Overall					$T = 25 °C, V_{CC} = 2.75 V, RF = 1.96 GHz,$
RF Frequency Range		1500 to 2200		MHz	LO=2170MHz@-7dBm, IF=210MHz
LO Frequency Range		1200 to 2200		MHZ	
IF Frequency Range		0.1 to 250		MHZ	
Bias Current		2.5	2.8	mA	LNA, mixer and preamp for bias circuitry.
US PCS - LNA		2.5	2.0	IIIA	LINA, mixer and preamp for bias circuity.
Gain	13.5	15.0		dB	
Noise Figure	15.5	1.4	1.8	dB	
Input IP3	+6.0	+7.0	1.0	dBm	IIP3 is adjustable (see plots for setting).
input il 3	+0.0	+7.0		ubiii	ISET1 (pin 14) external resistor sets current
					consumption and performance.
Input VSWR			2:1		
Output VSWR			2:1		
Current at Input IP3		7	7.5	mA	
US PCS - LNA Bypass					
Gain	-6	-5		dB	
Noise Figure		5	5.5	dB	
Input IP3	+23.0	+26.0		dBm	
Input VSWR			2:1		
Output VSWR			2:1		
Current		0		mA	
US PCS - Mixer - High Gain					$1 k\Omega$ balanced load.
Mode					
Gain	10	12		dB	
Noise Figure		6.5	7.5	dB	
Input IP3	+3.0	+4.0		dBm	IIP3 is adjustable (see plots for setting).
RF to IF Isolation		>45		dB	ISET2 (pin 13) external resistor sets current
					consumption and performance.
Input VSWR			2:1		
Output VSWR			2:1		
Current		12	13	mA	
US PCS - Mixer - Low Gain	<u> </u>	12	.0		1kΩ balanced load.
Mode					
Gain	0	1.5		dB	
Noise Figure	, J	1.0	16	dB	
Input IP3	+13.0	+14.0		dBm	IIP3 is adjustable
RF to IF Isolation		>45		dB	ISET2 (pin 13) external resistor sets current
		-		-	consumption and performance.
Input VSWR			2:1		
Output VSWR			2:1		
Current		7.5	8.0	mA	

Devementer	Specification			Unit	Condition		
Parameter	Min.	Тур.	Typ. Max.		Condition		
KPCS - LNA							
Gain	14.5	16.0		dB			
Noise Figure		1.4	1.8	dB			
Input IP3	+5.0	+6.0		dBm	IIP3 is adjustable (see plots for setting). ISET1 (pin 14) external resistor sets current consumption and performance.		
Input VSWR			2:1				
Output VSWR			2:1				
Current at Input IP3		7	7.5	mA			
KPCS - LNA Bypass							
Gain	-6	-5		dB			
Noise Figure		5.0	5.5	dB			
Input IP3	+23.0	+26.0		dBm			
Input VSWR			2:1				
Output VSWR			2:1				
Current		0		mA			
KPCS - Mixer - High Gain					$1 k\Omega$ balanced load.		
Mode							
Gain	10	12		dB			
Noise Figure		6.5	7.5	dB			
Input IP3	+2.5	+3.5		dBm	IIP3 is adjustable (see plots for setting).		
RF to IF Isolation		>45		dB	ISET2 (pin 13) external resistor sets current consumption and performance.		
Input VSWR			2:1				
Output VSWR			2:1				
Current		12	13	mA			
KPCS - Mixer - Low Gain					$1 k\Omega$ balanced load.		
Mode							
Gain	0	1.5		dB			
Noise Figure		15	16	dB			
Input IP3	+13.0	+14.0		dBm	IIP3 is adjustable		
RF to IF Isolation		>45		dB	ISET2 (pin 13) external resistor sets current consumption and performance.		
Input VSWR			2:1				
Output VSWR			2:1				
Current		7.5	8.0	mA			

Devenuetor	5	Specificatio	n	11	Condition	
Parameter	Min.	Тур.	Max.	Unit	Condition	
GPS - LNA						
Gain		16		dB		
Noise Figure		1.4		dB		
Input IP3		+7.0		dBm	IIP3 is adjustable. ISET1 (pin 14) external resistor sets current consumption and performance	
Current at Input IP3		7		mA	mance.	
GPS - Mixer						
Gain		17		dB		
Noise Figure		6		dB		
Input IP3		-5.0		dBm	IIP3 is adjustable. ISET1 (pin 14) external resistor sets current consumption and performance.	
Current at Input IP3		16		mA		
GPS - Cascaded						
Gain		31		dB		
Noise Figure		1.8		dB		
Input IP3		-19.0		dBm	IIP3 is adjustable. ISET1 (pin 14) external resistor sets current consumption and performance.	
Current at Input IP3		23		mA	manoo.	
Local Oscillator Input						
Input Level	-10	-7	0	dBm		
LO to RF Isolation		>40	Ũ	dB	Any gain state.	
LO to LNA Isolation		>60		dB	Any gain state.	
LO Current Buffer		4.5	5.0	mA	I _{CC2} when LO signal is present	
US PCS - Cascade -					LNA High Gain/Mixer High Gain	
LNA High/Mixer High					Assuming 3dB loss of filter	
Gain		24		dB	IF 1, $1 k\Omega$ balanced load.	
Noise Figure		2.2		dB	,	
Input IP3		-8.0		dBm	Single sideband.	
Total Current		26		mA		
US PCS - Cascade -					LNA High Gain/Mixer Low Gain	
LNA High/Mixer Low					Assuming 3dB loss of filter	
Gain		13.5		dB	IF 1, 1 k Ω balanced load.	
Noise Figure		5.3		dB		
Input IP3		+1.0		dBm	Single sideband.	
Total Current		21		mA		
US PCS - Cascade - LNA Low/Mixer High					LNA Low Gain/Mixer High Gain Assuming 3dB loss of filter	
Gain		4		dB	IF 1, 1k Ω balanced load.	
Noise Figure		14.5		dB		
Input IP3		+12.0		dB	Single sideband.	
Total Current		19		mA		
US PCS - Cascade -					LNA Low Gain/Mixer Low Gain	
LNA Low/Mixer Low					Assuming 3dB loss of filter	
Gain		-6.5		dB	IF 1, 1 k Ω balanced load.	
Noise Figure		23		dB		
Input IP3		+20.5		dB	Single sideband.	
Total Current		14		mA		

Demonster		Specificatio	n	11		
Parameter	Min.	Тур.	Max. Unit		Condition	
KPCS - Cascade -					LNA High Gain/Mixer High Gain	
LNA High/Mixer High					Assuming 3dB loss of filter	
Gain		25		dB	IF 1, 1 k Ω balanced load.	
Noise Figure		2.2		dB		
Input IP3		-9.5		dBm	Single sideband.	
Total Current		26		mA		
KPCS - Cascade -					LNA High Gain/Mixer Low Gain	
LNA High/Mixer Low					Assuming 3dB loss of filter	
Gain		14.5		dB	IF 1, 1 k Ω balanced load.	
Noise Figure		5.3		dB		
Input IP3		+1.0		dBm	Single sideband.	
Total Current		21		mA		
KPCS - Cascade -					LNA Low Gain/Mixer High Gain	
LNA Low/Mixer High					Assuming 3dB loss of filter	
Gain		4		dB	IF 1, 1k Ω balanced load.	
Noise Figure		14.5		dB		
Input IP3		+12.0		dB	Single sideband.	
Total Current		19		mA		
KPCS - Cascade -					LNA Low Gain/Mixer Low Gain	
LNA Low/Mixer Low					Assuming 3dB loss of filter	
Gain		-6.5		dB	IF 1, 1 k Ω balanced load.	
Noise Figure		23		dB		
Input IP3		+22		dB	Single sideband.	
Total Current		14		mA		
Power Supply						
Voltage	2.7	3.0	3.3	V		

Pin	Function	Description	Interface Schematic
1	ENABLE	Power down pin. A logic "low" turns the part off. A logic "high" (>1.6V) turns the part on.	
2	VCC1	Supply Voltage for the LNA, mixer, bias, and logic circuitry. External RF and IF bypassing is required. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane.	See pin 20.
3	VCC2	Supply Voltage for the LO buffer amplifier. External RF and IF bypass- ing is required. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capaci- tors should connect immediately to ground plane.	
4	LO IN	Mixer LO Input Pin.	
5	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	
6	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	
7	IF+	CDMA IF Output pin. This is a balanced output. The internal circuitry, in conjunction with an external matching/bias inductor to V _{CC} , sets the operating impedance. This inductor is typically incorporated in the matching network between the output and IF filter. The part is designed to drive a 1 k Ω load. Because this pin is biased to V _{CC} , a DC blocking capacitor must be used if the IF filter input has a DC path to ground. See Application Schematic.	IF1+ GND2 IF1-
8	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	
9	IF-	Same as pin 7, except complementary output.	See pin 6.
10	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	
11	LNA2 E	Emitter for LNA2. Increasing the inductance on this pin will reduce the mixer gain, increase IP3 and noise figure.	
12	MIX IN	Mixer RF Input Pin. This pin is internally DC biased and should be DC blocked if connected to a device with DC present. External matching network sets RF and IF impedance for optimum performance.	
13	ISET2	This pin is used to set the bias current and IIP3 of the mixer amplifier using a resistor to ground. See plots for values and current settings.	
14	ISET1	This pin is used to set the bias current and IIP3 of the LNA amplifier using a resistor to ground. See plots for values and current settings.	
15	LNA OUT	LNA output pin. Open collector.	See pin 20.
16	MIX GAIN	CMOS compatible signal controlling mixer gain mode. Setting this sig- nal high places the mixer in the high gain mode. Setting this signal low places the mixer in low gain mode by bypassing and shutting off the mixer buffer amplifier current.	
17	LNA GAIN	CMOS compatible signal controlling LNA gain mode. Setting this signal high places the LNA in the high gain mode. Setting this signal low bypasses the LNA and shuts off the LNA bias current.	
18	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	
19	NC	No connection. For isolation purposes, this pin is connected to the ground plane.	

Pin	Function	Description	Interface Schematic
20	LNA IN	RF Input pin. This pin is internally matched for optimum noise figure from a 50 Ω source.	
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with mul- tiple vias.	

Output Interface Network of the Mixer

L1, C1, C2, and R form a current combiner which performs a differential to single-ended conversion at the IF frequency and sets the output impedance. In most cases, the resonance frequency is independent of R and can be set according to the following equation:

$$f_{IF} = \frac{1}{2\pi \sqrt{\frac{L1}{2}(C_1 + 2C_2 + C_{EQ})}}$$

Where C_{EQ} is the equivalent stray capacitance and capacitance looking into pins 7 and 9. An average value to use for C_{EQ} is 2.5pF.

R can then be used to set the output impedance according to the following equation:

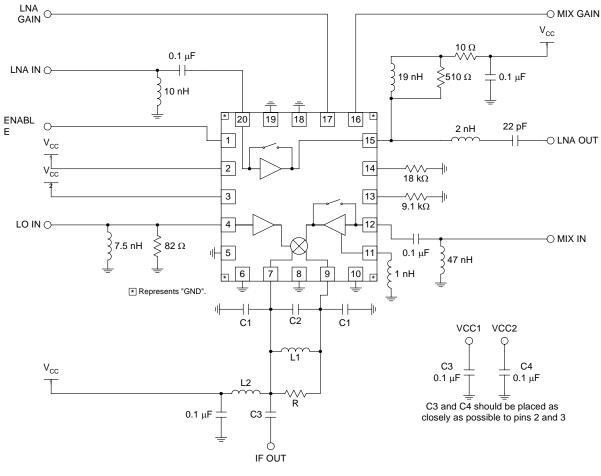
$$R = \left(\frac{1}{4 \cdot R_{OUT}} - \frac{1}{R_P}\right)^{-1}$$

where R_{OUT} is the desired output impedance and R_P is the parasitic equivalent parallel resistance of L1.

 C_2 should first be set to 0 and C1 should be chosen as high as possible (suggested less than 20pF), while maintaining an R_P of L1 that allows for the desired R_{OUT} . If the self-resonant frequencies of the selected C1 produce unsatisfactory linearity performance, their values may be reduced and compensated for by including C2 capacitor with a value chosen to maintain the desired F_{IF} frequency.

L2 and C3 serve dual purposes. L2 serves as an output bias choke, and C3 serves as a series DC block.

In addition, L2 and C3 may be chosen to form an impedance matching network if the input impedance of the IF filter is not equal to R_{OUT}. Otherwise, L2 is chosen to be large (suggested 120nH) and C3 is chosen to be large (suggested 22nF) if a DC path to ground is present in the IF filter, or omitted if the filter is DC blocked.

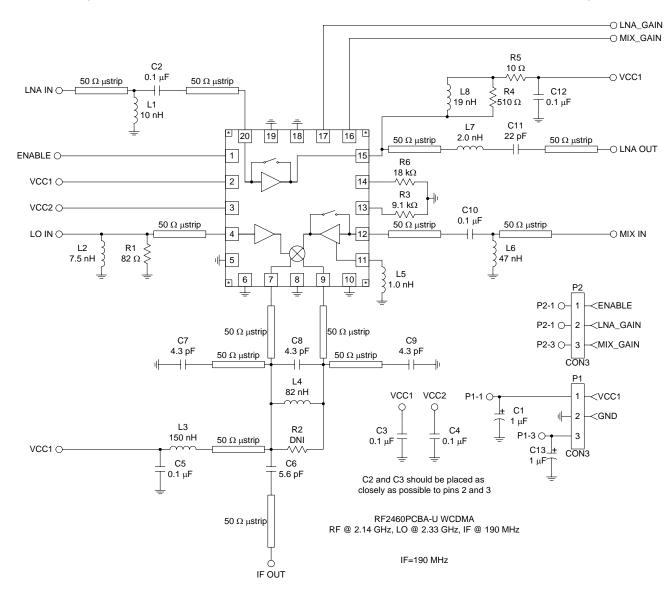


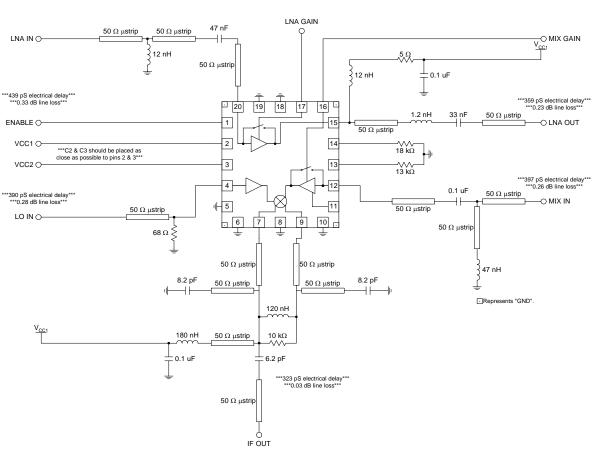
Application Schematic - US PCS

	C1 (pF)	C2 (pF)	C3 (pF)	L1 (nH)	L2 (nH)	R (Ω)
US PCS, IF = 210 MHz	4	3	6	82	110	4.7 k
Korean PCS, IF = 220 MHz	3.6	2	7	82	120	4.7 k
GPS, IF = 184 MHz	8.2	DNI	6.2	120	180	10 k
US PCS, IF = 184 MHz	8	3	6	82	110	4.7 k

Application Schematic - W-CDMA

(See W-CDMA charts for lab measurements at the end of the data sheet)





Application Schematic - GPS RF=1575MHz, IF=184MHz, LO=1759MHz

Current Measurement

To measure only the current of the different circuitry in the evaluation board, use the following procedure.

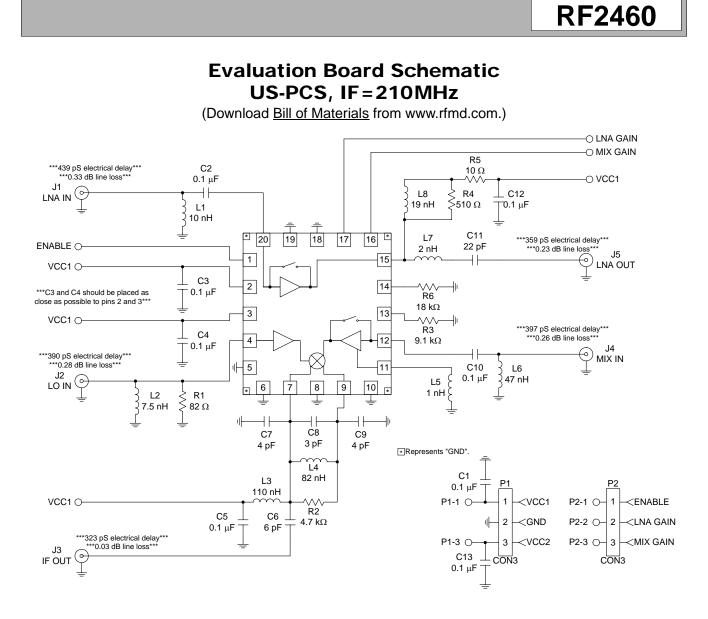
First, replace the bias choke inductor at the output of the mixer (L3 for US-PCS) with a 1 Ω resistor. The voltage across the resistor will represent the mixer current. Terminate all SMA connections at 50 Ω .

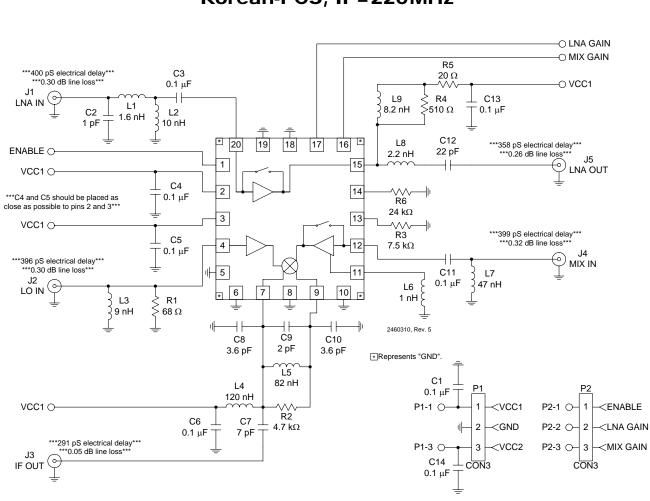
Second, follow the table below.

		CONDITION						
	Current (mA)	V _{CC1}	V _{CC2}	EN	LNA Gain	Mix Gain		
I _{CC} Total	25.82	1	1	1	1	1		
LNA Off	18.77	1	1	1	0	1		
Mixer Preamp Off	14.28	1	1	1	0	0		
V _{CC2} Off	10.05	1	0	1	0	0		
Mixer Current	7.72	1	0	1	0	0		

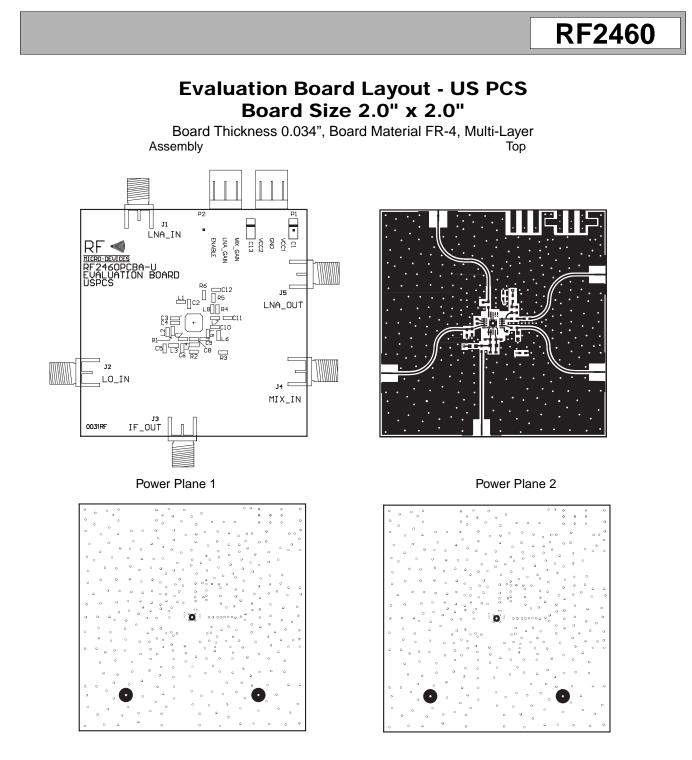
Therefore,

LNA (Bypass) =	(Computer Simulation)	=	0mA
LNA (High Gain) =	25.82-18.77	=	7.05mA
Mixer (Preamp) =	18.77-14.28	=	4.49mA
Mixer =	(Measured)	=	7.70mA
Bias =	10.05-7.7	=	2.35 mA
LO Circuitry (V_{CC2}) =	14.28-10.05	=	4.23mA
		-	25.82 mA

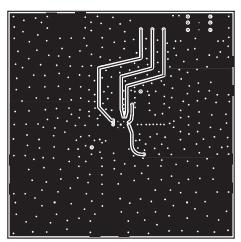




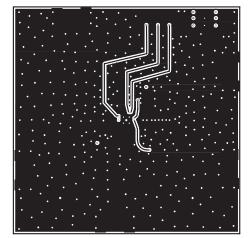
Evaluation Board Schematic Korean-PCS, IF=220MHz

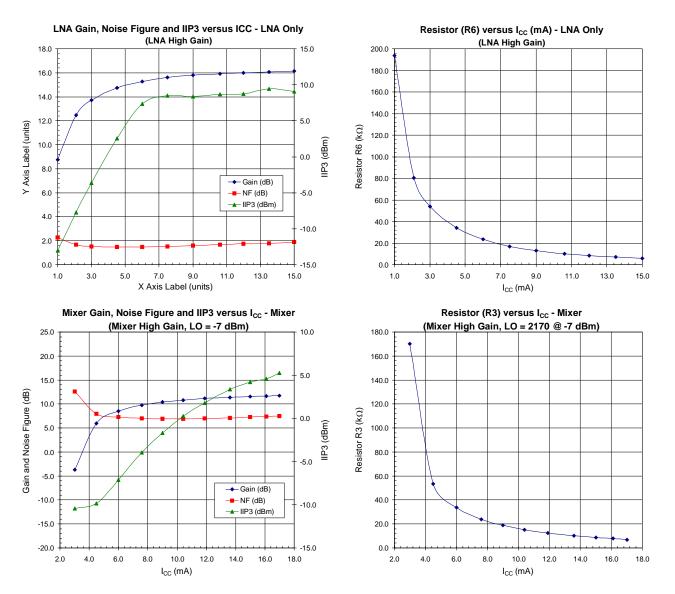


Back



Evaluation Board Layout - Korean PCS J1 ĽNA_IN RF W RF2460PCBA-K EVALUATION BOARD KPCS c2 LNA_GAN MIX_GAIN ENABLE J5 □ LNA_OUT _9[]R4 C11 J2 LO_IN J4 □ 2460310(5)K MIX_IN J3 0032_RCM IF_OUT Power Plane 1 Power Plane 2 Back





US-PCS

Special Instructions (Board loss, taking into consideration description in the schematic) <u>LNA</u>

V_{CC1}=V_{CC2}=Enable=2.75V; Mix Gain=0.0V

To measure I_{CC} LNA only:

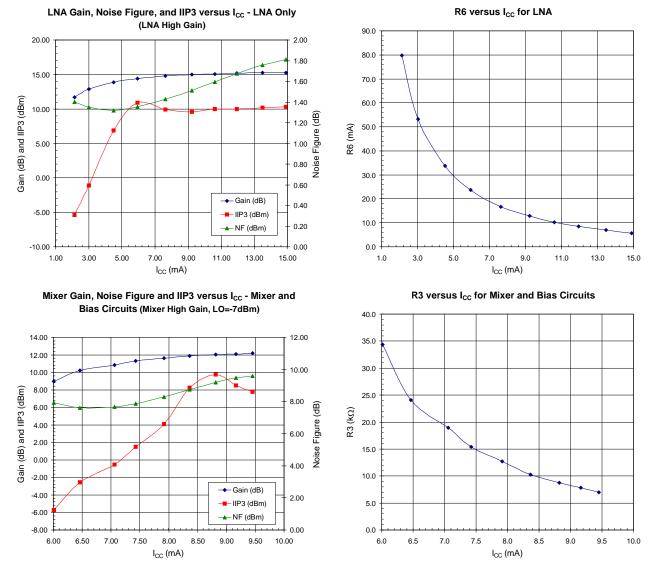
LNA Gain was switched between 0V and 2.75V, and record the delta current.

Mixer

V_{CC1}=V_{CC2}=Enable=Mix Gain=2.75V; LNA Gain=0.0V

To measure I_{CC} Mixer (LNA should be in bypass mode and LO signal should be present):

Mixer Current=Total IC Current-LO Circuitry (~4.23mA) (See "Current Measurement" section for more details) V_{CC2} only affects LO current buffer and R6 doesn't affect the mixer current.



W-CDMA (See W-CDMA Application Schematic)

 $\ensuremath{\text{Instructions}}$ (Board loss, taking into consideration description in the W-CDMA schematic) $\underline{\text{LNA}}$

I_{CC} LNA current=total current (V_{CC}=LNA Gain=2.75)-total current (V_{CC}=2.75; LNA Gain=0)

To measure I_{CC} LNA only:

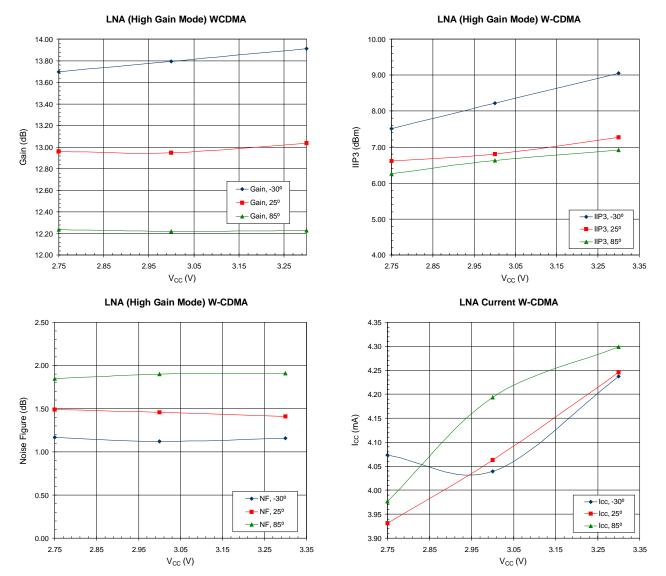
LNA Gain was switched between 0V and 2.75V, and record the delta current.

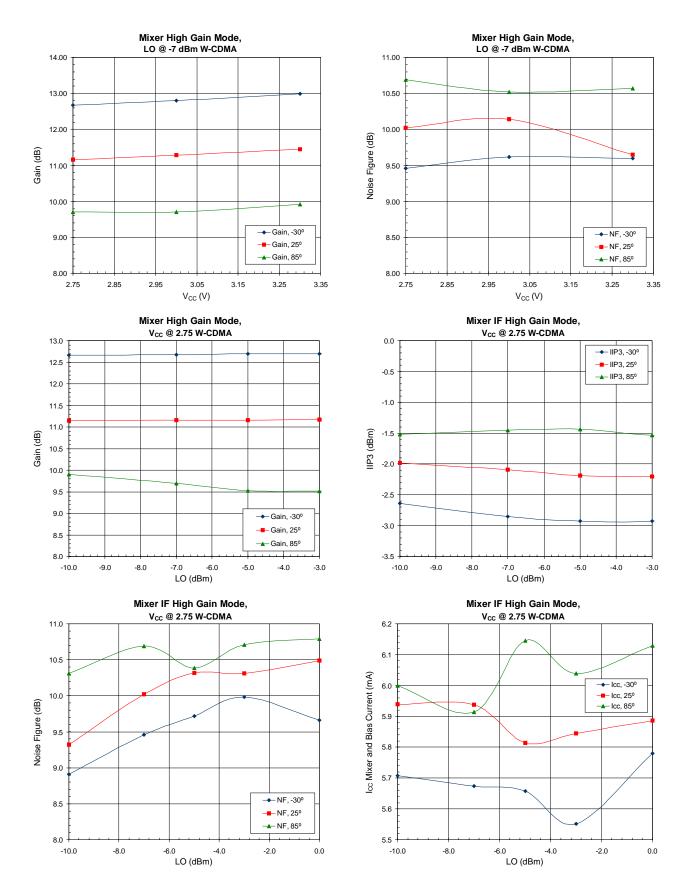
Mixer

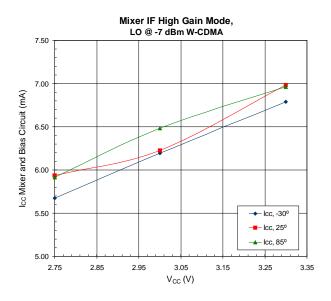
I_{CC} Mix and Bias Current=Total Current (V_{CC1}=EN=V_{CC2}=Mix Gain=2.75; LNA Gain=0)-total current (V_{CC1}=EN=2.75; Mix Gain=LNA Gain=V_{CC2}=0)

LO signal should be present. V_{CC2} only affects LO current buffer and R6 doesn't affect the mixer current.

By using a R6=39k Ω and R3=24k Ω , the following results were obtained. RF=2140MHz, LO=2330MHz, IF=190MHz.







PCB Design Requirements

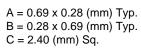
PCB Surface Finish

The PCB surface finish used for RFMD's qualification process is electroless nickel, immersion gold. Typical thickness is 3µinch to 8µinch gold over 180µinch nickel.

PCB Land Pattern Recommendation

PCB land patterns are based on IPC-SM-782 standards when possible. The pad pattern shown has been developed and tested for optimized assembly at RFMD; however, it may require some modifications to address company specific assembly processes. The PCB land pattern has been developed to accommodate lead and package tolerances.

PCB Metal Land Pattern



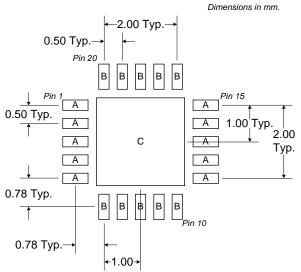


Figure 1. PCB Metal Land Pattern (Top View)

PCB Solder Mask Pattern

Liquid Photo-Imageable (LPI) solder mask is recommended. The solder mask footprint will match what is shown for the PCB metal land pattern with a 2mil to 3mil expansion to accommodate solder mask registration clearance around all pads. The center-grounding pad shall also have a solder mask clearance. Expansion of the pads to create solder mask clearance can be provided in the master data or requested from the PCB fabrication supplier.

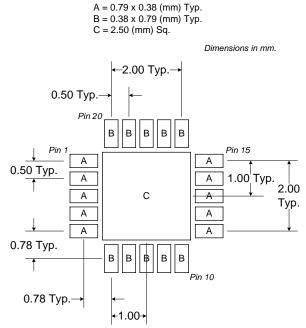


Figure 2. PCB Solder Mask Pattern (Top View)

Thermal Pad and Via Design

The PCB land pattern has been designed with a thermal pad that matches the die paddle size on the bottom of the device.

Thermal vias are required in the PCB layout to effectively conduct heat away from the package. The via pattern has been designed to address thermal, power dissipation and electrical requirements of the device as well as accommodating routing strategies.

The via pattern used for the RFMD qualification is based on thru-hole vias with 0.203mm to 0.330mm finished hole size on a 0.5mm to 1.2mm grid pattern with 0.025mm plating on via walls. If micro vias are used in a design, it is suggested that the quantity of vias be increased by a 4:1 ratio to achieve similar results.